


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	ADG/23/13965	
1.3 Title of PCI	Packing and labelling change according MSL 1	
1.4 Product Category	TCPP01-M12 TCPP03-M20	
1.5 Issue date	2023-04-28	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	KRAUSE INA
2.1.2 Phone	+49 89460062370
2.1.3 Email	ina.krause@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Stephane CHAMARD
2.1.2 Marketing Manager	Philippe LEGER
2.1.3 Quality Manager	Jean-Paul REBRASSE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	(Not Defined)	Subcontractors in Malaysia (TCPP01-M12) and China (TCPP03-M20)

4. Description of change

	Old	New
4.1 Description	Desiccant & dry bag packing (corresponding to MSL 3)	No desiccant and no dry bag (corresponding to MSL 1)
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	Packing	

5. Reason / motivation for change

5.1 Motivation	Adjustment between MSL 1 (Moisture Sensitivity Level 1) initial qualification and packing & labelling.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	MSL 1 on label.
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7. Timing / schedule

7.1 Date of qualification results	2023-04-18
7.2 Intended start of delivery	2023-07-28
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13965 Qualification reports.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-04-28

9. Attachments (additional documentations)

13965 Public product.pdf
13965 PCI TCPP01 TCPP03.pdf
13965 Qualification reports.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
3690355	T CPP01-M12	
	T CPP03-M20	

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